

## **Description**

The SI2333CDS uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})}$ , This device is suitable

for use as a load switch or in PWM applications.



SOT-23

#### **General Features**

 $V_{DS} = -18V, I_{D} = -6.5A$ 

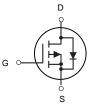
 $R_{DS(ON)}$  < 28m $\Omega$  @  $V_{GS}$ =-4.5V

## **Application**

Battery protection

Load switch

Uninterruptible power supply



P-Channel MOSFET

# **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
SI2333CDS	SOT-23	20P07	3000

### Absolute Maximum Ratings (TA=25 ℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V <sub>DS</sub>	Drain-Source Voltage	-18	V
Vgs	Gate-Source Voltage	±12	V
I <sub>D</sub>	Drain Current-Continuous	-6.5	Α
Ірм	Drain Current-Pulsed (Note 1)	-15	Α
P <sub>D</sub>	Maximum Power Dissipation	2	W
ТЈ,Тѕтс	Operating Junction and Storage Temperature Range	-55 To 150	°C
RеJA	Thermal Resistance, Junction-to-Ambient (Note 2)	74	°C/W

## P-Channel Enhancement Mode MOSFET

# Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-	-18	-	V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V,V <sub>GS</sub> =0V	-	-	-1	μA	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±8V,V <sub>DS</sub> =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=-250\mu A$	-0.45	-0.7	-1.0	V	
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4.1A	-	20	28	mΩ	
Diani-Source Off-State Resistance		$V_{GS}$ =-2.5V, $I_{D}$ =-3A	-	27	36		
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-5V,I <sub>D</sub> =-3.5A	-	8.5	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C <sub>lss</sub>	V <sub>DS</sub> =-4V,V <sub>GS</sub> =0V,	-	980	-	PF	
Output Capacitance	C <sub>oss</sub>	F=1.0MHz	-	450	-	PF	
Reverse Transfer Capacitance	C <sub>rss</sub>	1 = 1.0WH12	-	250	ı	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t <sub>d(on)</sub>		-	12	ı	nS	
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-4 $V$ , $I_{D}$ =-3.3 $A$ ,	-	35	ı	nS	
Turn-Off Delay Time	$t_{d(off)}$	$R_L=-1.2\Omega, V_{GEN}=-4.5V, R_g=1\Omega$	-	30	ı	nS	
Turn-Off Fall Time	t <sub>f</sub>		-	10	ı	nS	
Total Gate Charge	Qg		-	7.8	ı	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =-4V, $I_{D}$ =-4.1A, $V_{GS}$ =-4.5V	-	1.2	1	nC	
Gate-Drain Charge	$Q_{gd}$		-	1.6	ı	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-1.6A	-	-	-1.2	V	
Diode Forward Current (Note 2)	Is		-	-	1.6	Α	
	•						

#### Notes:

- **1.** Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



# **Typical Characteristics**

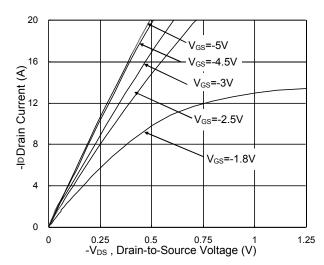


Fig.1 Typical Output Characteristics

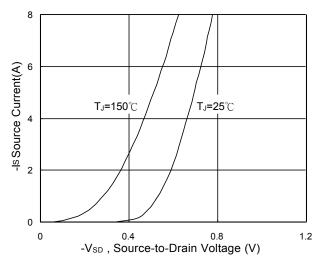


Fig.3 Forward Characteristics Of Reverse

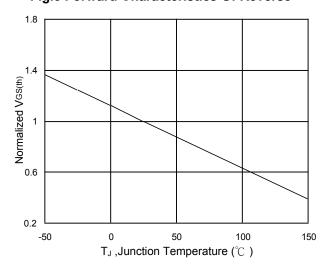


Fig.5 Normalized  $V_{\text{GS(th)}}$  vs.  $T_{\text{J}}$ 

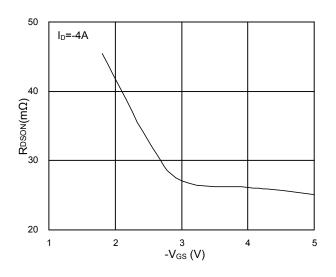


Fig.2 On-Resistance vs. Gate-Source

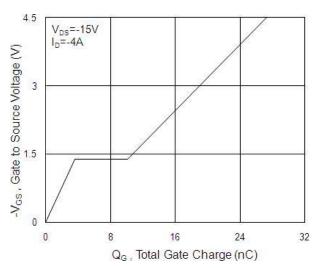


Fig.4 Gate-Charge Characteristics

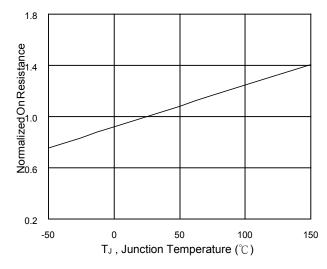
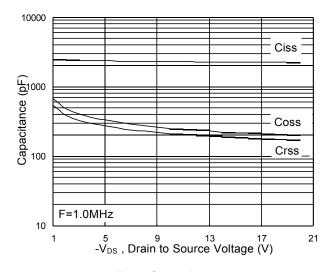


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





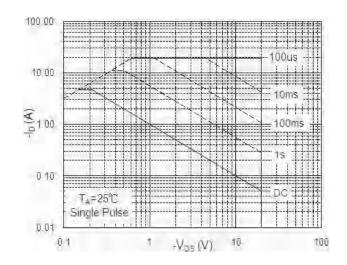


Fig.7 Capacitance

Fig.8 Safe Operating Area

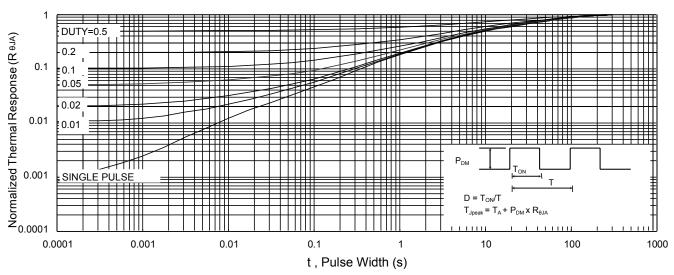
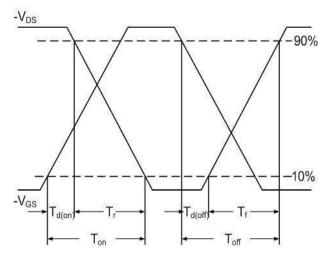
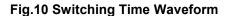


Fig.9 Normalized Maximum Transient Thermal Impedance





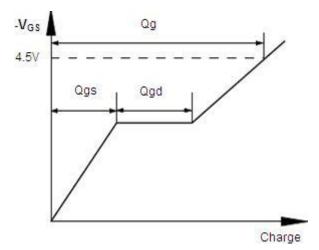
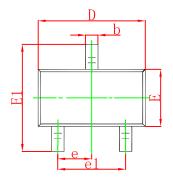
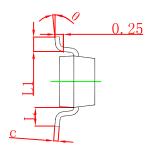


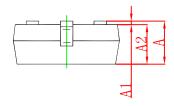
Fig.11 Gate Charge Waveform



# **SOT-23 Package Outline Dimensions**

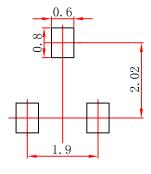






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950	TYP 0.		37 TYP	
e1	1.800	2.000	0.071	0.079	
Ĺ	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

# **SOT-23 Suggested Pad Layout**



- Note: 1.Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
  3.The pad layout is for reference purposes only.



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